APPLICA	BLE STAN	DARD									
	FING Voltage Current		-55 °C to 85 °C	C	Storage temperature -10%		-10℃ TO 50℃(Packed o	10°C TO 50°C(Packed condition)			
RATING			30V AC / DC		Operating or storage humidity range		Re	Relative humidity 90 % MAX (Not dewe			
			Appli 0.3 A			le cable		t=0.3±0.03mm, Gold	0.3±0.03mm, Gold plating		
	1		SPEC	IFICA	TION	S					
TI	EM		TEST METHOD			-	REQU	IREMENTS	QT	AT	
CONSTR	UCTION	I			I					1	
Seneral exa	mination	Visually a	and by measuring instrumen	nt.	A	ccording to c	Irawing	l.	×	×	
Marking		Confirme	med visually.			(note 1)			×	×	
ELECTR	ICAL CHA	RACTE	RISTICS							4	
/oltage proc	of	90 V AC	for 1 min.		N	lo flashover o	or brea	kdown.	×	—	
nsulation re	sistance	100 V D0	<u>).</u>		5	0 MΩ MIN.			×	—	
Contact resid	stance	AC 20 m	VMAX 1mA		1	100 mQ MAX				!	
	Starice	AC 20 III	AC 20 MV MAX , 1 MA .						~	_	
					Ir	Including FPC	bulk r	esistance (L=8mm)		<u> </u>	
			EKISTICS	lo	9	No electric		optionuity of 1		1	
noration		0.75 mm	5 mm, for 10 cycles in 3 axial directions.			<ul> <li>No electrical discontinuity of 1 µs.</li> <li>Contact resistance: 100 mQ MAX.</li> </ul>			×		
Shock		981 m/s <sup>2</sup>	$81 \text{ m/s}^2$ , duration of pulse 6 ms			<ol> <li>No damage, crack and looseness of parts.</li> </ol>			×	1 - 1	
Maakari		at 3 times	s in 3 both axial directions.				• .	400 0 1111	<u> </u>	ļ'	
viechanical	operation	10 time	10 times insertions and extractions.			1) Contact resistance: $100 \text{ m}\Omega$ MAX.			×		
FPC insertion force Measure		Measure	asured by applicable EPC			No damage, crack and looseness of parts. Insertion force - Direction of insertion			×	<u> </u>	
(Thickne			ess of FPC shall be t=0.30mm			2.6+0.14 × n N MAX ( <i>note 2</i> )					
		at initial	condition.)		(r	(n: Number of contacts)					
FPC retentio	on force	Measure	d by applicable FPC		R	Retention force : Direction of extraction			×	—	
		(Inicknes	condition.)	n	5. (r	+0.07 × n N ľ n: Number of	MIN ( <i>n</i>	ote3)			
					(1	I. NUMBER OF	contac	(5)			
Corrosion sa		Exposed	at 35+2 °C 5 % salt water	r sprav	(1	) Contact re	sistanc	e: 100 mO MAX			
		for 96 h.		i Spidy	Ċ				^		
Rapid change of		<b>Temperature</b> -55→+15 <sub>TO</sub> +35→+85→+15 <sub>TO</sub> +35°C			5°C (1	① Contact resistance: 100 mΩ MAX.			×	—	
temperature		Time	Time $30 \rightarrow 2 \text{ to } 3 \rightarrow 30 \rightarrow 2 \text{ to } 3 \text{ min}$			2 Insulation resistance: 50 M $\Omega$ MIN.					
Damp hoat		Under	Under 5 cycles.			③ No damage, crack and looseness of parts.					
uamp neat (steady state)		Exposed at $40\pm2$ °C, Relative humidity 90 to 95 %. 96 h.							×	_	
Damp heat,c	cyclic	Exposed	Exposed at -10 to +65 °c,			) Contact re	sistanc	e: 100 mΩ MAX.	×	—	
Rel		Relative	elative humidity 90 to 96 %,			2 Insulation resistance: 1 M $\Omega$ MIN.					
10 cycle			s, TOTAL 240 h.			(At high humidity)					
						<ul> <li>(At dry)</li> <li>(At dry)</li> <li>(At dry)</li> </ul>					
								-	_	<u> </u>	
I											
COUN	IT DE	SCRIPTI	ON OF REVISIONS		DESIGN	NED		CHECKED		DATE	
3	DIS-		IS-F-00010250 SE.		SE. YOKOY	OKOYAMA		HY. YAMAZAKI		20210713	
REMARK						APPR	OVED	VED NF. MIYAZAKI		0823	
						CHEC	CKED	YN. TAKASHITA	2017	0823	
						DESIC	GNED	HH. MURAKAMI	2017	0823	
Unless otherwise specified, re			efer to IEC 60512.			DRAWN		HH. MURAKAMI		0823	
Note QT:Q	ualification Te	st AT:As	surance Test X:Applicable T	Fest	DRA	WING NO.		ELC-368163-9	9-00	)	
۲Ŋ	SI	PECIFICATION SHEET			PART N	PART NO. FH6		62-**S-0. 25SHW (99)			
	HIR	OSF FI				10	CI 580		$\mathbf{\Lambda}$	1/2	
						NU.	0L00U			., _	

	SPECIFICATI	ONS		
ITEM	TEST METHOD	REQUIREMENTS	QT	AT
Dry heat	Exposed at 85±2°C, 96 h.	① Contact resistance: 100 mΩ MAX.	×	_
Cold	Exposed at -55±3°C, 96 h.	② No damage, crack and looseness of parts	×	_
Sulphur dioxide [JIS C 60068-2-42]	Exposed at 40±2 °C, Relative humidity 80±5% 25±5 ppm for 96 h.	① Contact resistance: 100 mΩ MAX.	×	—
Hydrogen sulphide [JIS C 60068-2-43]	Exposed at 40±2 °C, Relative humidity 80±5% , 10 to 15 ppm for 96 h.		×	—
Solderability	Soldered at solder temperature, 245±3°C for immersion duration,3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	—
Resistance to soldering heat	<ol> <li>1) Reflow soldering : Peak TMP. 250 °C MAX . Reflow TMP. over 220 °C 60 to 90 sec. Number of reflow : 2 times</li> <li>2) Soldering irons : TMP. 350±10 °C for 5±1 sec .</li> </ol>	No deformation of case of excessive looseness of the terminals. ( <i>note 4</i> )	×	—

## (note 1)

This product features top-contact point.

"One Action Lock" completes FPC lock just by inserting the FPC.

Do not operate the locking-lever when inserting the FPC.

## (note 2)

Do not insert the FPC to this product at an angle.

## (note 3)

There's a case which FPC retention force doesn't fulfill the value, because FPC specification affects the result of FPC retention force.

Stabilize the FPC to PCB or something fixed, if pull-up or pull-down force is exepected to be applied to the FPC.

## (note 4)

Blisters which may be generated on the housing do not affect product performance.

Note QT:C	evalification Test AT:Assurance Test X:Applicable Test	DRAWIN	IG NO.	ELC-368163-99-00			
HRS	SPECIFICATION SHEET	PART NO.	FH62-**S-0. 25SHW(99)				
	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	♪	2/2	